

### Description

The SX6P06MI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -60V$   $I_D = -6A$

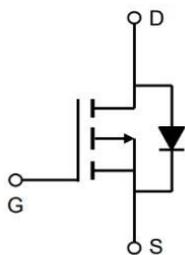
$R_{DS(ON)} < 90m\Omega$  @  $V_{GS}=10V$

### Application

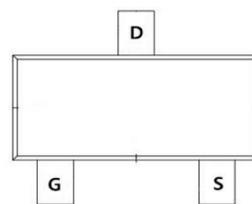
Brushless motor

Load switch

Uninterruptible power supply



SOT-23-3L



### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

| Symbol                | Parameter  | Rating     | Units        |
|-----------------------|--|------------|--------------|
| $V_{DS}$              | Drain-Source Voltage                                   | -60        | V            |
| $V_{GS}$              | Gate-Source Voltage                                    | $\pm 20$   | V            |
| $I_D@T_c=25^\circ C$  | Continuous Drain Current, $V_{GS}$ @ -10V <sup>1</sup> | -6         | A            |
| $I_D@T_c=100^\circ C$ | Continuous Drain Current, $V_{GS}$ @ -10V <sup>1</sup> | -4.3       | A            |
| $I_{DM}$              | Pulsed Drain Current <sup>2</sup>                      | -26        | A            |
| EAS                   | Single Pulse Avalanche Energy <sup>3</sup>             | 29.8       | mJ           |
| $I_{AS}$              | Avalanche Current                                      | -24.4      | A            |
| $P_D@T_c=25^\circ C$  | Total Power Dissipation <sup>4</sup>                   | 31.3       | W            |
| $T_{STG}$             | Storage Temperature Range                              | -55 to 150 | $^\circ C$   |
| $T_J$                 | Operating Junction Temperature Range                   | -55 to 150 | $^\circ C$   |
| $R_{\theta JA}$       | Thermal Resistance Junction-Ambient <sup>1</sup>       | 125        | $^\circ C/W$ |
| $R_{\theta JC}$       | Thermal Resistance Junction-Case <sup>1</sup>          | 40         | $^\circ C/W$ |

**P-Channel Electrical Characteristics (T<sub>J</sub> =25 °C, unless otherwise noted)**

| Symbol                 | Parameter                                      | Conditions   | Min. | Typ.  | Max. | Unit |
|------------------------|--|--|------|-------|------|------|
| BVDSS                  | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA   | -60  | ---   | ---  | V    |
| ΔBVDSS/ΔT <sub>J</sub> | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25°C , I <sub>D</sub> =-1mA   | ---  | -0.03 | ---  | V/°C |
| RDS(ON)                | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =-10V , I <sub>D</sub> =-3A  | ---  | 80    | 90   | mΩ   |
|                        |  | V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-2A   | ---  | 100   | 115  |      |
| VGS(th)                | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA  | -1.2 | -1.75 | -2.5 | V    |
| IDSS                   | Drain-Source Leakage Current                   | V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C                               | ---  | ---   | 1    | uA   |
|                        |  | V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C                               | ---  | ---   | 5    |      |
| IGSS                   | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V  | ---  | ---   | ±100 | nA   |
| gfs                    | Forward Transconductance                       | V <sub>DS</sub> =-5V , I <sub>D</sub> =-3A   | ---  | 8.5   | ---  | S    |
| Q <sub>g</sub>         | Total Gate Charge (-4.5V)                      | V <sub>DS</sub> =-48V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-3A                             | ---  | 12.1  | ---  | nC   |
| Q <sub>gs</sub>        | Gate-Source Charge                             |  | ---  | 2.2   | ---  |      |
| Q <sub>gd</sub>        | Gate-Drain Charge                              |  | ---  | 6.3   | ---  |      |
| Td(on)                 | Turn-On Delay Time                             | V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V ,<br>R <sub>G</sub> =3.3Ω ,<br>I <sub>D</sub> =-1A | ---  | 9.2   | ---  | ns   |
| T <sub>r</sub>         | Rise Time                                      |  | ---  | 20.1  | ---  |      |
| Td(off)                | Turn-Off Delay Time                            |  | ---  | 46.7  | ---  |      |
| T <sub>f</sub>         | Fall Time                                      |  | ---  | 9.4   | ---  |      |
| Ciss                   | Input Capacitance                              | V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz   | ---  | 1137  | ---  | pF   |
| Coss                   | Output Capacitance                             |  | ---  | 76    | ---  |      |
| Crss                   | Reverse Transfer Capacitance                   |  | ---  | 50    | ---  |      |
| IS                     | Continuous Source Current <sup>1,5</sup>       | V <sub>G</sub> =V <sub>D</sub> =0V , Force Current   | ---  | ---   | -13  | A    |
| VSD                    | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C                                 | ---  | ---   | -1.2 | V    |

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

Typical Characteristics

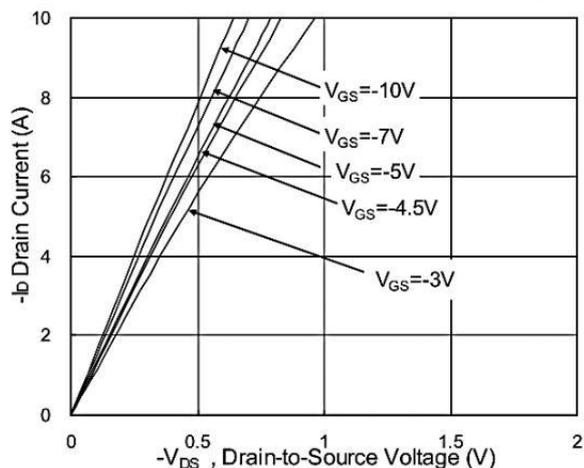


Fig.1 Typical Output Characteristics

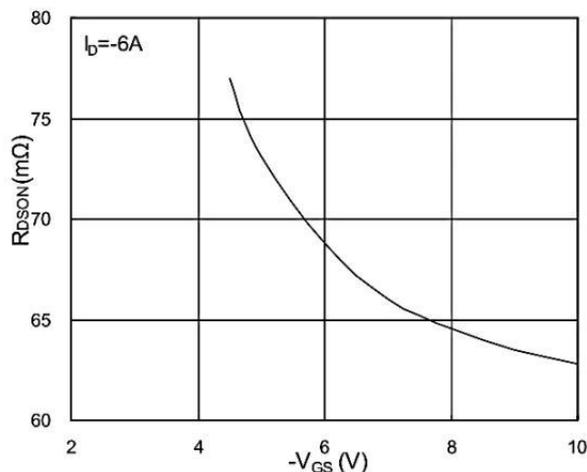


Fig.2 On-Resistance v.s Gate-Source

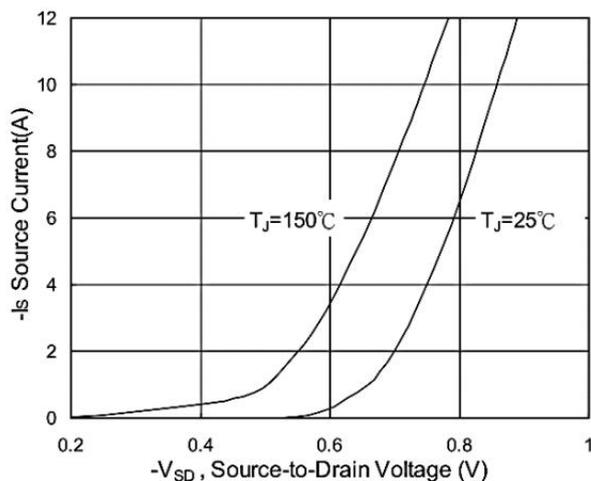


Fig.3 Forward Characteristics of Reverse

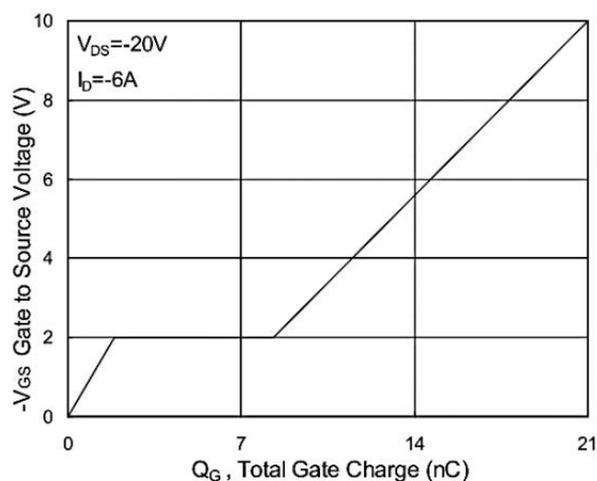


Fig.4 Gate-Charge Characteristics

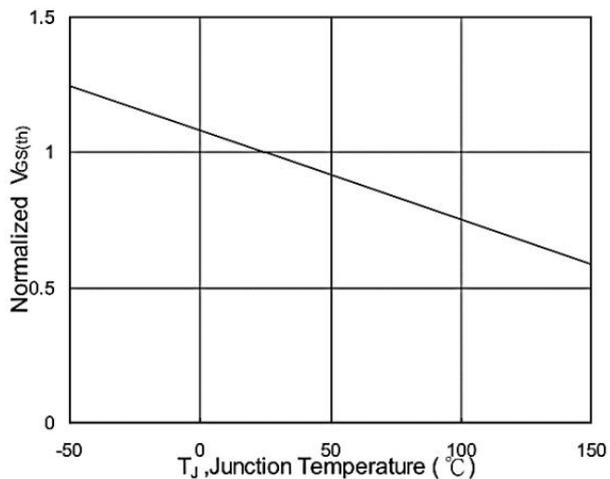


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$

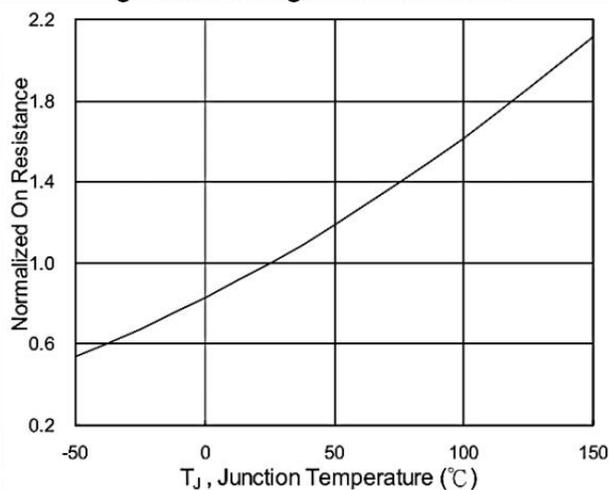


Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$

Typical Characteristics

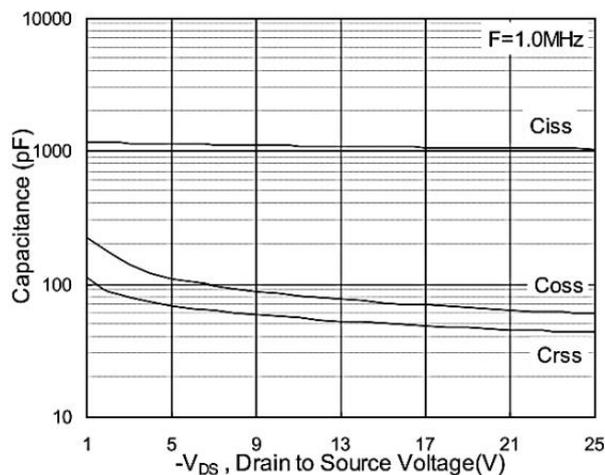


Fig.7 Capacitance

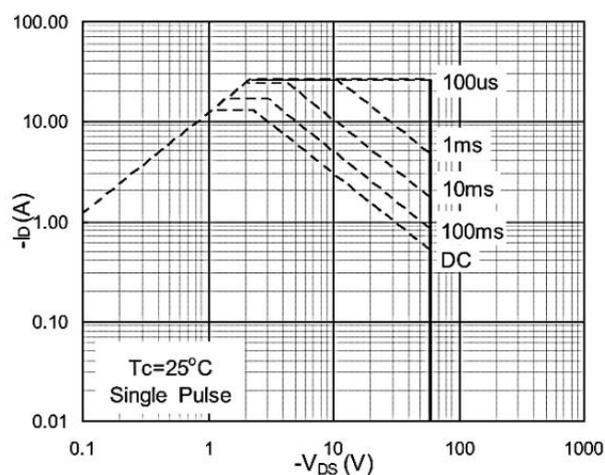


Fig.8 Safe Operating Area

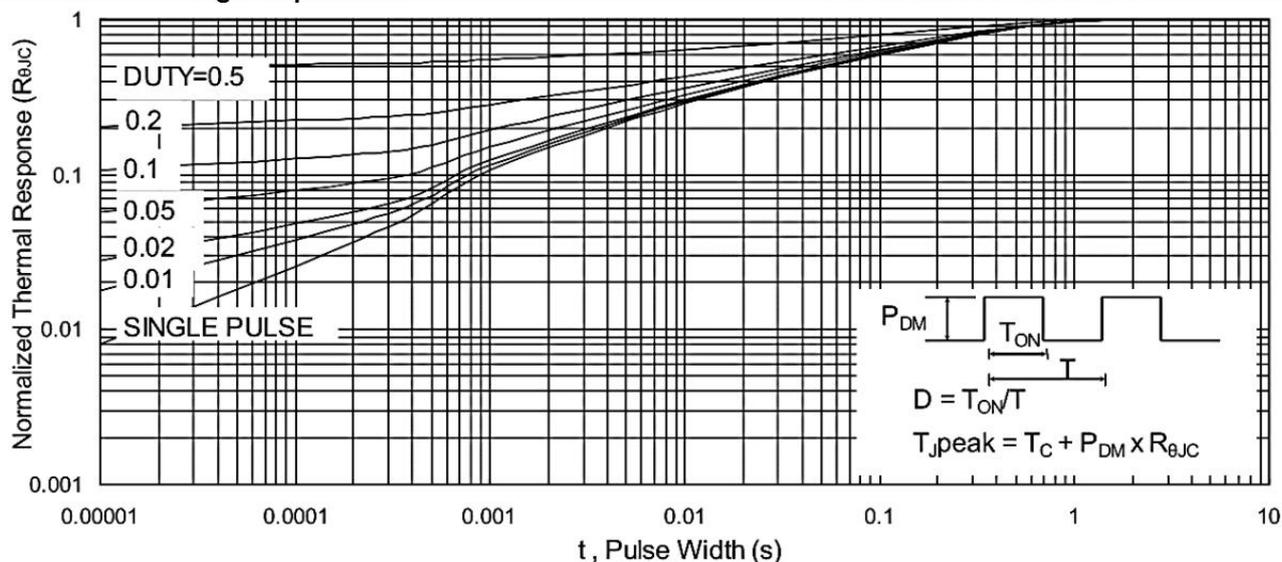


Fig.9 Normalized Maximum Transient Thermal Impedance

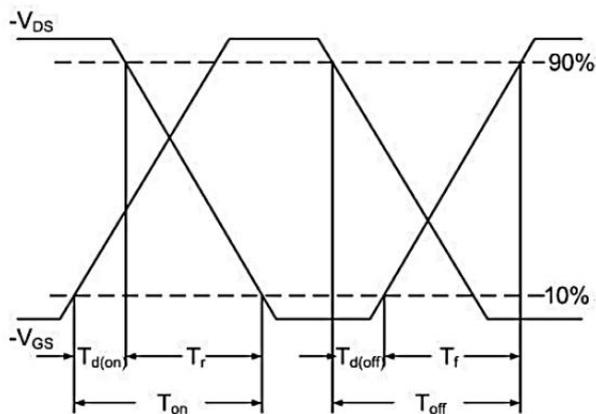


Fig.10 Switching Time Waveform

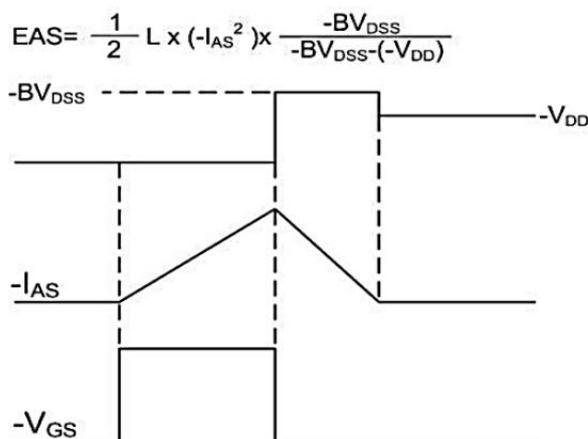
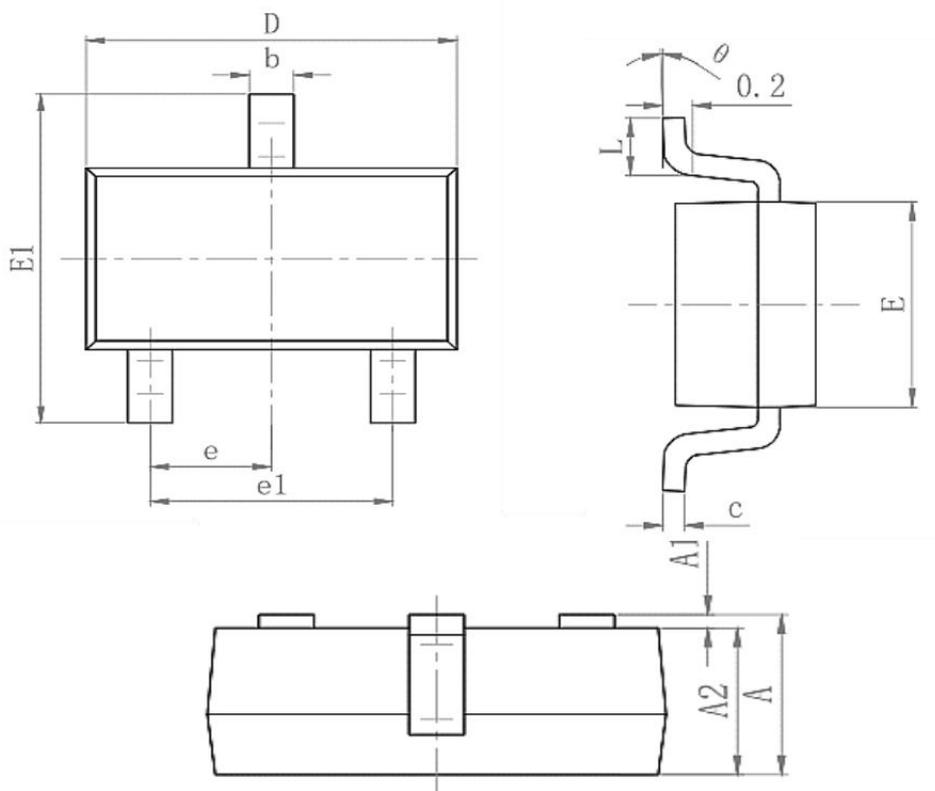


Fig.11 Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times (-I_{AS}^2) \times \frac{-BV_{DSS}}{-BV_{DSS} - (-V_{DD})}$$

## Package Mechanical Data-SOT23-3-XC-Single



| Symbol   | Dimensions In Millimeters |       |
|----------|---------------------------|-------|
|          | Min.                      | Max.  |
| A        | 1.050                     | 1.250 |
| A1       | 0.000                     | 0.100 |
| A2       | 1.050                     | 1.150 |
| b        | 0.25                      | 0.45  |
| c        | 0.100                     | 0.200 |
| D        | 2.820                     | 3.020 |
| E        | 1.5                       | 1.7   |
| E1       | 2.650                     | 2.950 |
| e        | 0.950(BSC)                |       |
| e1       | 1.800                     | 2.000 |
| L        | 0.300                     | 0.500 |
| $\theta$ | 0°                        | 8°    |

### Package Marking and Ordering Information

| Product ID | Pack     | Marking | Qty(PCS) |
|------------|----------|---------|----------|
| TAPING     | SOT23-3L |         | 3000     |